

10-21-2008

Form PTO-1595 (Rev. 08/08)
OMB No. 0651-0027 (exp. 9/30/2008)

U.S. DEPARTMENT OF COMMERCE
United States Patent and Trademark Office




103530849

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies): Akira Hayashida (08/28/2008), Masaaki Ueno (08/28/2008), Masakazu Shimada (08/28/2008), Masashi Sugishita (08/28/2008), Additional name(s) of conveying party(ies) attached? <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No	2. Name and address of receiving party(ies) Name: <u>HITACHI KOKUSAI ELECTRIC INC.</u> Internal Address: _____ Street Address: _____ 14-1, Sotokanda 4-chome, Chiyoda-ku City: <u>Tokyo</u> State: _____ Country: <u>JAPAN</u> Zip: <u>101-8980</u> Additional name(s) & address(es) attached? <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
3. Nature of conveyance/Execution Date(s): Execution Date(s): in parentheses after inventor name <input type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Change of Name <input type="checkbox"/> Security Agreement <input type="checkbox"/> Joint Research Agreement <input type="checkbox"/> Government Interest Assignment <input type="checkbox"/> Executive Order 9424, Confirmatory License <input checked="" type="checkbox"/> Other Request to correct the second inventor's first name to an Assignment document previously recorded at Reel 021591 Frame 0555	

4. Application or patent number(s): <input type="checkbox"/> This document is being filed together with a new application. A. Patent Application No.(s) <u>12/213,824</u> B. Patent No.(s) Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	
--	--

5. Name and address to whom correspondence concerning document should be mailed: Name: <u>RADER, FISMAN & GRAUER PLLC</u> Internal Address: <u>Atty. Dkt.: KKI-0117</u> Street Address: <u>1233 20th Street, N.W. Suite 501</u> City: <u>Washington</u> State: <u>DC</u> Zip: <u>20036</u> Phone Number: <u>(202) 955-3750</u> Fax Number: <u>(202) 955-3751</u> Email Address: _____	6. Total number of applications and patents involved: <u>1</u> 7. Total fee (37 CFR 1.21(h) & 3.41) \$ _____ <input type="checkbox"/> Authorized to be charged by credit card <input type="checkbox"/> Authorized to be charged to deposit account <input type="checkbox"/> Enclosed <input type="checkbox"/> None required (government interest not affecting title) 8. Payment Information a. Credit Card Last 4 Numbers _____ Expiration Date _____ b. Deposit Account Number <u>18-0013</u> Authorized User Name <u>Toshikatsu Imaizumi</u>
--	--

9. Signature:  _____ Toshikatsu Imaizumi - 61,648 Name of Person Signing	_____ October 20, 2008 Date Total number of pages including cover sheet, attachments, and documents: <u>10</u>
--	---

**RECORDATION FORM COVER SHEET (PTO-1595)
(supplemental sheet)**

Additional Conveying Party(ies)/Execution Date(s) (1. Continued):

Toshimitsu Miyata (08/29/2008), Kimio Kitamura (08/18/2008), Kenji Tanaka (08/18/2008), and Jyunichi Nishihara (08/22/2008)

Additional Assignees (2. Continued):

Assignee Name: TEITOKUSHA CO., LTD.

Internal Address:

Street Address: 1-5-32, Shigita, Joto-ku, Osaka-shi

City: Osaka State: Osaka City: Osaka State: Osaka

Assignee Name: _____

Internal Address: _____

Street Address: _____

City: _____ State: _____ Country: _____ Zip: _____

Assignee Name: _____

Internal Address: _____

Street Address: _____

City: _____ State: _____ Country: _____ Zip: _____

Additional Applications and/or Patents (4. Continued):

Additional Patent Application Numbers

4A. Continued:

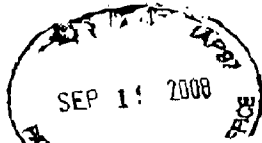
Additional Patent Numbers

4B. Continued:

Additional numbers attached?

Yes

No



Form PTO-1595 (Rev. 08/08)
OMB No. 0651-0027 (exp. 9/30/2008)

DEPARTMENT OF COMMERCE
Patent and Trademark Office

09-24-2008

RECORDED
PAT



103526346

new address(es) below.

To the Director of the U.S. Patent and Trademark Office

1. Name of conveying party(ies):

Akira Hayashida (08/28/2008), Masaaki Ueno
(08/28/2008), Masakazu Shimada (08/28/2008),
Masashi Sugishita (08/28/2008),

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): In parentheses after inventor name

- Assignment Merger Change of Name
- Security Agreement Joint Research Agreement
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other

2. Name and address of receiving party(ies)

Name: HITACHI KOKUSAI ELECTRIC INC.

Internal Address:

Street Address:

14-1, Sotokanda 4-chome,
Chiyoda-ku

City: Tokyo

State:

Country: JAPAN Zip: 101-8980

Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s):

A. Patent Application No.(s)
12/213,824

This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: RADER, FISMAN & GRAUER PLLC

Internal Address: Atty. Dkt.: KKI-0117

Street Address: 1233 20th Street, N.W.
Suite 501

City: Washington

State: DC Zip: 20036

Phone Number: (202) 955-3750

Fax Number: (202) 955-3751

Email Address:

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____
Expiration Date _____

b. Deposit Account Number 18-0013
Authorized User Name Toshikatsu Imaizumi

9. Signature:

September 19, 2008

Date

Toshikatsu Imaizumi - 61,648
Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

6

09/23/2008 DAYONE 00000655 180013 12213624

01 FC:8021

40.00 DA

Docket Number: KKI-0117

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

HEATING APPARATUS, SUBSTRATE PROCESSING APPARATUS EMPLOYING THE SAME, METHOD OF MANUFACTURING SEMICONDUCTOR DEVICES, AND INSULATOR

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, HITACHI KOKUSAI ELECTRIC INC., a Japanese corporation with offices at 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 101-8980 JAPAN, and TEITOKUSHA CO., LTD. a Japanese corporation with offices at 1-5-32, Shigita, Joto-ku, Osaka-shi, Osaka 536-0015 JAPAN (hereinafter referenced as ASSIGNEES) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of Ten Dollar (\$10.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements

Attorney Docket No. KKI-0117

in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

Serial Number: 12/213,824, Filing Date: 06/25/2008.

This assignment executed on the dates indicated below.

Akira HAYASHIDA Akira Hayashida Aug. 28, 2008
Signature Date

Masaaki UENO Masaaki Ueno Aug. 28, 2008
Signature Date

Masakazu SHIMADA M. Shimada Aug. 28, 2008
Signature Date

Masashi SUGISHITA Masashi Sugishita Aug. 28, 2008
Signature Date

Toshimitsu MIYATA Toshimitsu Miyata Aug. 29, 2008
Signature Date

Kimio KITAMURA _____
Signature Date

Attorney Docket No. KKI-0117

in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

Serial Number: 12/213,824, Filing Date: 06/25/2008.

This assignment executed on the dates indicated below.

Akira HAYASHIDA

Signature

Date

Masaaki UENO

Signature

Date

Masakazu SHIMADA

Signature

Date

Masashi SUGISHITA

Signature

Date

Toshimitsu MIYATA

Signature

Date

Kimio KITAMURA

Signature

Date

Kimio Kitamura

August 18, 2008

PATENT

REEL: 021708 FRAME: 0538

Attorney Docket No. KKI-0117

Kenji TANAKA 田中健司 August 18, 2008
Signature Date

Jyunichi NISHIHARA 西尾淳一 August 22, 2008
Signature Date